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#### **IMPACT**

TE Internal #: 2007788-1

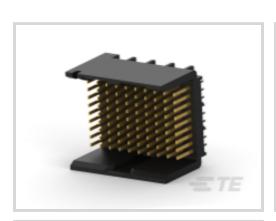
High Speed Backplane Connectors, 90 Position, Mating Alignment, Polarization Mating Alignment Type, 9 Row, 10 Column, PCB

Mount Header, IMPACT

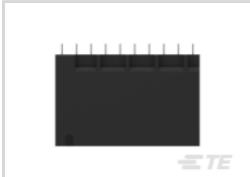
View on TE.com >

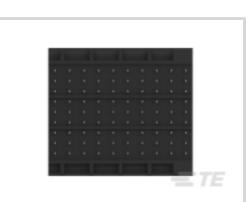


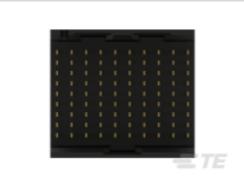
Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Connector System: Board-to-Board

Number of Positions: 90

Row-to-Row Spacing: 1.35 mm [ .053 in ]

Mating Alignment: With

Mating Alignment Type: Polarization

### **Features**

### **Product Type Features**

Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ground Positions	30
Number of Pairs	30
Stackable	No
Number of Signal Positions	60
Number of Positions	90
Number of Rows	9
Number of Columns	10
PCB Mount Orientation	Vertical



Guide Location	Unguided	
Electrical Characteristics		
Impedance	100 Ω	
Operating Voltage	30 VAC	
Signal Characteristics		
Number of Differential Pairs per Column	3	
Data Rate	20 – 25 Gb/s	
Body Features		
Primary Product Color	Black	
Contact Features		
Contact Mating Area Length	4.5 mm[.177 in]	
PCB Contact Termination Area Plating Material Thickness	.76 – 1.52 μm[30 – 60 μin]	
Contact Layout	Inline	
Contact Type	Pin	
Contact Underplating Material Thickness	1.27 μm[50 μin]	
Contact Mating Area Plating Material Thickness	.76 μm[29.92 μin]	
Contact Mating Area Plating Material	Gold	
PCB Contact Termination Area Plating Material Finish	Matte	
Contact Shape & Form	Dual Beam	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	Tin	
Contact Base Material Copper Alloy		
Contact Current Rating (Max)	.75 A	
Termination Features		
Termination Post & Tail Length	1.4 mm[.055 in]	
Termination Method to Printed Circuit Board	Through Hole - Press-Fit	
Mechanical Attachment		
Guide Hardware	Without	
Mating Retention	Without	
PCB Mount Retention	With	
PCB Mount Retention Type	Action/Compliant Tail	
Mating Alignment	With	



Mating Alignment Type	Polarization	
Connector Mounting Type	Board Mount	
Housing Features		
Number of Shrouded Sides	2	
End Wall Location	Open	
Housing Material	LCP - GF (Liquid Crystal Polymer)	
Centerline (Pitch)	1.9 mm[.075 in]	
Dimensions		
Connector Length	18.9 mm[.744 in]	
Connector Height	11.95 mm[.47 in]	
Connector Width	16.7 mm[.657 in]	
PCB Thickness (Recommended)	1 mm	
PCB Hole Diameter	.36 mm[.014 in]	
Row-to-Row Spacing	1.35 mm[.053 in]	
Usage Conditions		
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]	
Operation/Application		
Circuit Application	Signal	
Industry Standards		
Compatible With Approved Standards Products	CSA Certified, UL E28476	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Method	Box & Tube, Package	

### **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235)



$\square$	n 0 +	aantain	REACH	CV/IIC
DOES	$\Gamma(C)$	contain	KFAU.H	$\Sigma V \square U$

· ·	gen - Br, Cl, F, I < 900 ppm per ous material. Also BFR/CFR/PVC
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#### Solder Process Capability

Not applicable for solder process capability

#### Product Compliance Disclaimer

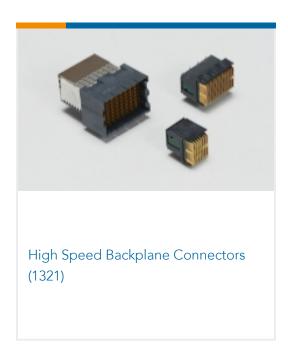
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

### **Compatible Parts**





### Also in the Series | IMPACT



## Customers Also Bought





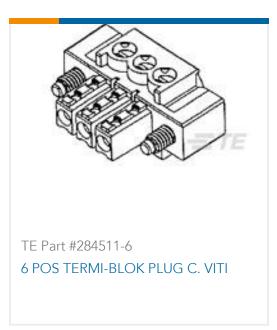


















### **Documents**

### **Product Drawings**

IMP100S,H,V3P10C,UG,OEW39,4.5

English

### **CAD Files**

**Customer View Model** 

ENG\_CVM\_CVM\_2007788-1\_B.2d\_dxf.zip

English

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2007788-1\_B.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2007788-1\_B.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

High Speed Backplane Connectors, 90 Position, Mating Alignment, Polarization Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, IMPACT



### 7-1773458-1\_IMPACT\_BACKPLANE\_CONNECTOR\_SYSTEM\_CATALOG

English

**Product Specifications** 

**Application Specification** 

English

Agency Approvals

Agency Approval Document

English